

# INFORMATION DISCLOSURE CITATION

(Use several sheets if necessary)

ATTY DOCKET NO.  
EN997075

SERIAL NO.  
09/346,358

J. S. Kresge et al.

FILING  
7/02/99

GROUP  
2811

10872 U.S. PAT.  
10/040745  
01/07/02

## U.S. PATENT DOCUMENTS

*EXAMINER INITIAL	DOCUMENT NUMBER	DATE	NAME	CLASS	SUBCLASS	FILING DATE IF APPROPRIATE
DA	5,072,075	12/10/91	Lee et al.	174/264		06/28/89
on	5,121,190	06/09/92	Hsiao et al.	357/80		03/14/90
on	5,483,421	01/09/96	Gedney et al.	361/771		03/09/92
on	5,574,630	12/12/96	Kresge et al.	361/792		05/11/95
on	5,615,087	03/25/97	Wieloch	361/719		11/03/95
on	5,798,563	08/25/98	Feilchenfeld et al.	257/668		01/28/97
on	5,894,173	04/13/99	Jacobs et al.	257/790		11/05/97
on	5,900,675	05/04/99	Appelt et al.	257/778		04/21/97

## FOREIGN PATENT DOCUMENTS

	DOCUMENT NUMBER	DATE	COUNTRY	CLASS	SUBCLASS	TRANSLATION	
						YES	NO

## OTHER DOCUMENTS (Including Author, Title, Date, Pertinent Pages, Etc.)

on		IBM Technical Disclosure Bulletin, Vol. 32, No. 3B, August 1989, "MULTILAYER POLYMER SUBSTRATE FOR DIRECT CHIP ATTACHMENT".

EXAMINER

*Boylston* 11-21-02

DATE CONSIDERED

\*EXAMINER: Initial if reference considered, whether or not citation is in conformance with MPEP 609; Draw line through citation if not in conformance and not considered. Include copy of this form with next communication to applicant.

# INFORMATION DISCLOSURE CITATION

(Use several sheets if necessary)

Docket Number (Optional)

EN9970

Application Number

09/346,355

Applicant(s)

J. S. Kresge et al.

Filing Date

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2811

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10/07/02

## U.S. PATENT DOCUMENTS

*EXAMINER INITIAL	REF	DOCUMENT NUMBER	DATE	NAME	CLASS	SUBCLASS	FILING DATE IF APPROPRIATE
<i>M</i>		5,838,063	11/17/98	Sylvester	257/704		11/08/96

## FOREIGN PATENT DOCUMENTS

	REF	DOCUMENT NUMBER	DATE	COUNTRY	CLASS	SUBCLASS	Translation	
							YES	NO

## OTHER DOCUMENTS (Including Author, Title, Date, Pertinent Pages, Etc.)


EXAMINER

*[Signature]*

DATE CONSIDERED

11-21-02

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10/040745  
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**U.S. PATENT DOCUMENTS**

*EXAMINER INITIAL	REF	DOCUMENT NUMBER	DATE	NAME	CLASS	SUBCLASS	FILING DATE IF APPROPRIATE
	AA						
	AB						
	AC						
	AD						
	AE						
	AF						
	AG						
	AH						
	AI						
	AJ						
	AK						

**FOREIGN PATENT DOCUMENTS**

REF	DOCUMENT NUMBER	DATE	COUNTRY	CLASS	SUBCLASS	Translation	
						YES	NO
AL							
AM							
AN							
AO							
AP							

**OTHER DOCUMENTS**

(Including Author, Title, Date, Pertinent Pages, Etc.)

"High Performance Carrier Technology: Materials And Fabrication", by Light et al, 1993 International Electronics Packaging Conference, San Diego, California, Volume One.

"High Performance Carrier Technology", by Heck et al, 1993 International Electronics Packaging Conference, San Diego, California, Volume One.

EXAMINER

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## U.S. PATENT DOCUMENTS

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	AG						
	AH						
	AI						
	AJ						
	AK						

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							YES	NO
	AL							
	AM							
	AN							
	AO							
	AP							

## OTHER DOCUMENTS (Including Author, Title, Date, Pertinent Pages, Etc.)

AR	"Process Considerations in the Fabrication of Teflon Printed Circuit Boards", by Light et al, 1994 Proceedings, 44 Electronic Components & Technology Conference, 5/94.

EXAMINER

DATE CONSIDERED

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Docket Number (Optional) EN997	Application Number 09/346,350
Applicant(s) Kresge et al.	
Filing Date 07/02/99	Group Art Unit 2841

2 U.S. PAT. & TM. OFF. / 040745 / 07/02

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	REF	DOCUMENT NUMBER	DATE	COUNTRY	CLASS	SUBCLASS	Translation	
							YES	NO
<i>mn</i>		JP 9-232376	09/05/97	Japan			✓	
<i>mn</i>		JP 10-209347	08/07/98	Japan			✓	
<i>mn</i>		JP 11-87560	03/30/99	Japan			✓	
<i>mn</i>		JP 2000-022071	01/21/00	Japan			✓	
<i>mn</i>		JP 6-112271	04/22/94	Japan			✓	


**SHEET 1      OF 2**

(Use several sheets if necessary)

**EN997**

09/346,356

Kresge et al.

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	REF	DOCUMENT NUMBER	DATE	COUNTRY	CLASS	SUBCLASS	Translation	
							YES	NO
BW		JP 2000-024150	01/25/00	Japan			✓	
DW		JP 1-307294	12/12/89	Japan			✓	


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**SHEET 2 OF 2**